

Patent

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CENTRAL FAX CENTER**MAR 17 2005**Customer No.: 31561
Docket No.10233-US-PA
Application No.: 10/605,602**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of

Applicant : Sung-Fei Wang
Application No. : 10/605,602
Filed : 10/13/2003
For : HEAT SINK FOR CHIP PACKAGE AND BONDING
METHOD THEREOF
Art Unit : 1734
Examiner : CHAN, SING P

TRANSMITTAL LETTER

002-1-703-872-9306

(Via fax: 1+ 4 pages)

Assistant Commissioner for Patents
Arlington, Virginia 22202

Dear Sir,

In response to the Office Action dated February 18, 2005(Paper No.: 20050216), please find the *Response to Office Action*, in 4 pages.

I believe that no fee is incurred. However, the Commissioner is authorized to charge any fees required in connection with the filing of this paper to account No. 50-2620 (Order No.: 10233 -US-PA)

Thank you for your assistance in the subject matter. If you have any questions, please feel free to contact me.

Respectfully Submitted,
JIANQ CHYUN Intellectual Property Office

Date: March 18, 2005By: Belinda Lee
Belinda Lee
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